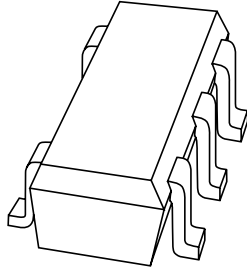


DATA SHEET



BZA800A-series Quadruple ESD transient voltage suppressor

Product data sheet
Supersedes data of 2000 May 01

2000 Sep 25



Quadruple ESD transient voltage suppressor

BZA800A-series

FEATURES

- ESD rating >8 kV, according to IEC1000-4-2
- SOT353 (SC-88A) surface mount package
- Common anode configuration.

APPLICATIONS

- Computers and peripherals
- Audio and video equipment
- Communication systems.

DESCRIPTION

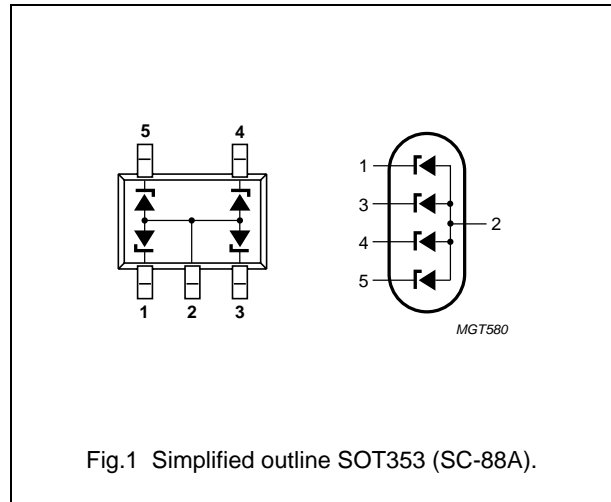
Monolithic transient voltage suppressor diode in a five lead SOT353 (SC-88A) package for 4-bit wide ESD transient suppression.

MARKING

TYPE NUMBER	MARKING CODE
BZA856A	Z1
BZA862A	Z2
BZA868A	Z3
BZA820A	Z4

PINNING

PIN	DESCRIPTION
1	cathode 1
2	common anode
3	cathode 2
4	cathode 3
5	cathode 4



Quadruple ESD transient voltage suppressor

BZA800A-series

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
I_Z	working current	$T_{amb} = 25\text{ °C}$	–	note 1	mA
I_F	continuous forward current	$T_{amb} = 25\text{ °C}$	–	200	mA
I_{FSM}	non-repetitive peak forward current	$t_p = 1\text{ ms}$; square pulse	–	3.75	A
P_{tot}	total power dissipation	$T_{amb} = 25\text{ °C}$	–	335	mW
P_{ZSM}	non repetitive peak reverse power dissipation: BZA856A, BZA862A, BZA868A, BZA820A	square pulse; $t_p = 1\text{ ms}$; see Fig.3	–	24	W
			–	17	W
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C

Note

- DC working current limited by $P_{tot(max)}$.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	all diodes loaded	370	K/W

Quadruple ESD transient voltage suppressor

BZA800A-series

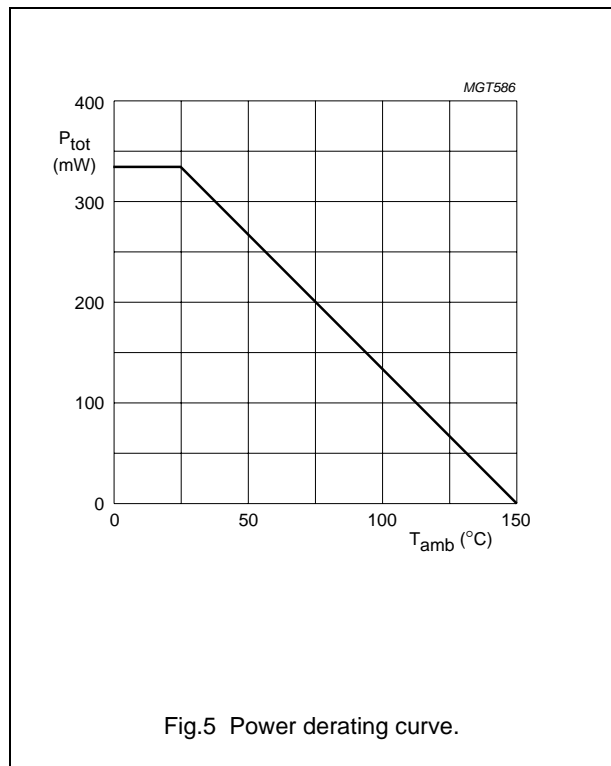
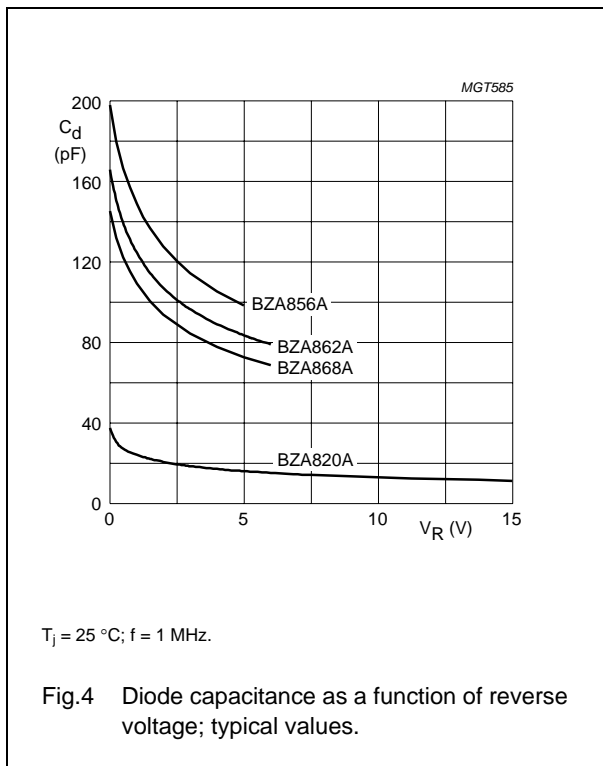
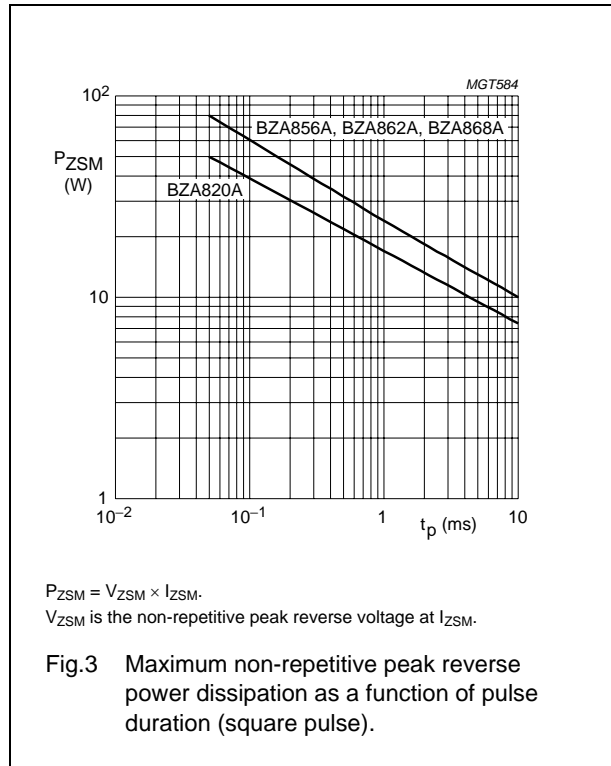
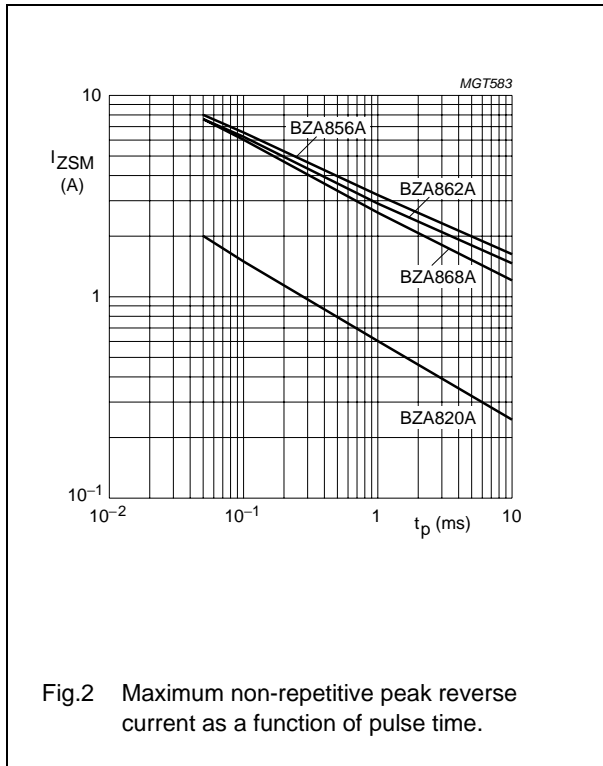
ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	forward voltage	$I_F = 200\text{ mA}$	–	–	1.3	V
I_R	reverse current					
	BZA856A	$V_R = 3\text{ V}$	–	–	2000	nA
	BZA862A	$V_R = 4\text{ V}$	–	–	700	nA
	BZA868A	$V_R = 4.3\text{ V}$	–	–	200	nA
V_Z	working voltage	$I_Z = 1\text{ mA}$				
	BZA856A		5.32	5.6	5.88	V
	BZA862A		5.89	6.2	6.51	V
	BZA868A		6.46	6.8	7.14	V
r_{diff}	differential resistance	$I_Z = 1\text{ mA}$				
	BZA856A		–	–	400	Ω
	BZA862A		–	–	300	Ω
	BZA868A		–	–	200	Ω
S_Z	temperature coefficient	$I_Z = 1\text{ mA}$				
	BZA856A		–	–0.2	–	mV/K
	BZA862A		–	1.8	–	mV/K
	BZA868A		–	3	–	mV/K
C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 0$				
	BZA856A		–	–	240	pF
	BZA862A		–	–	200	pF
	BZA868A		–	–	180	pF
I_{ZSM}	non-repetitive peak reverse current	$t_p = 1\text{ ms}; T_{amb} = 25\text{ °C}$				
	BZA856A		–	–	3.2	A
	BZA862A		–	–	2.9	A
	BZA868A		–	–	2.6	A
	BZA820A		–	–	0.6	A

Quadruple ESD transient voltage suppressor

BZA800A-series



Quadruple ESD transient voltage suppressor

BZA800A-series

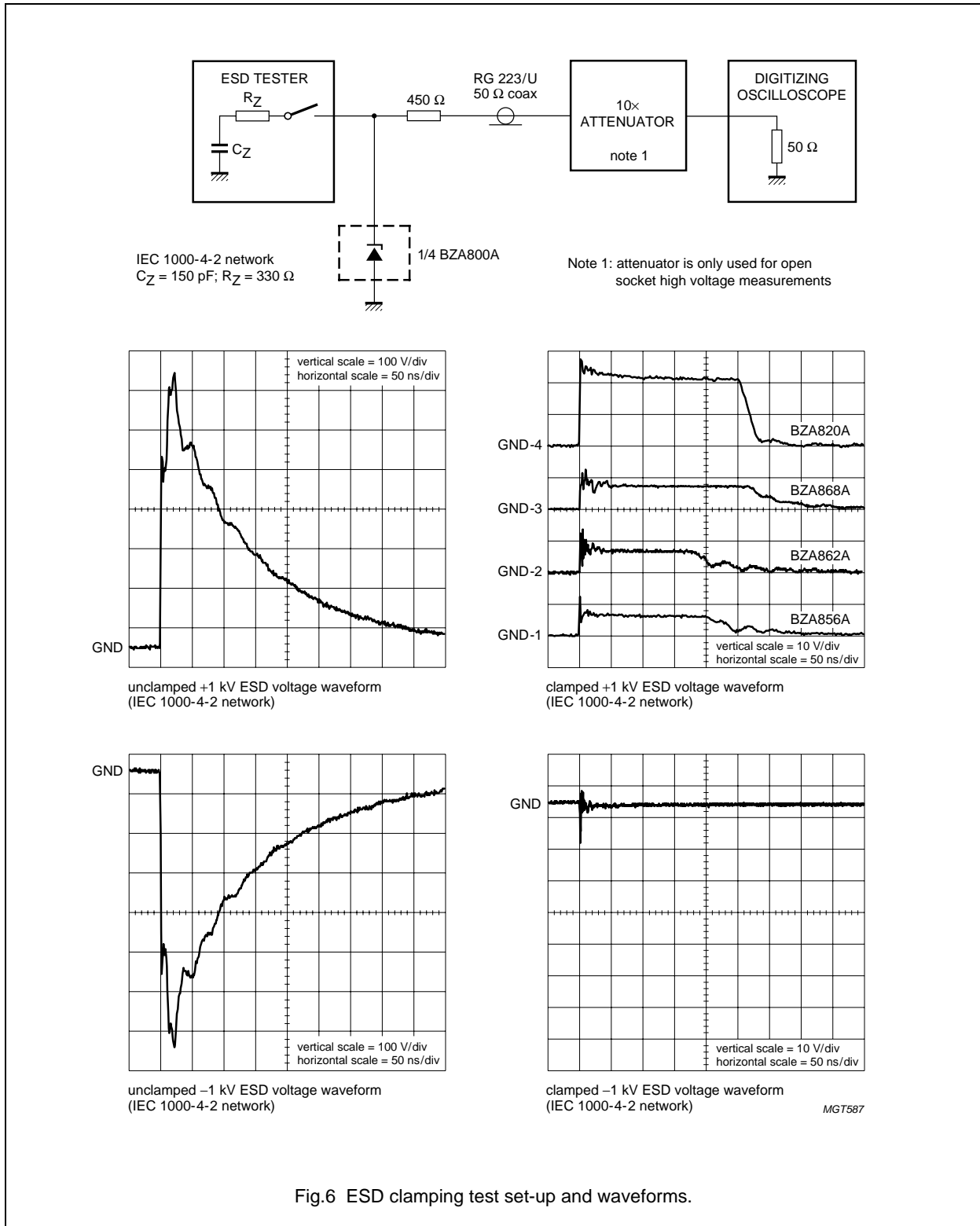


Fig.6 ESD clamping test set-up and waveforms.

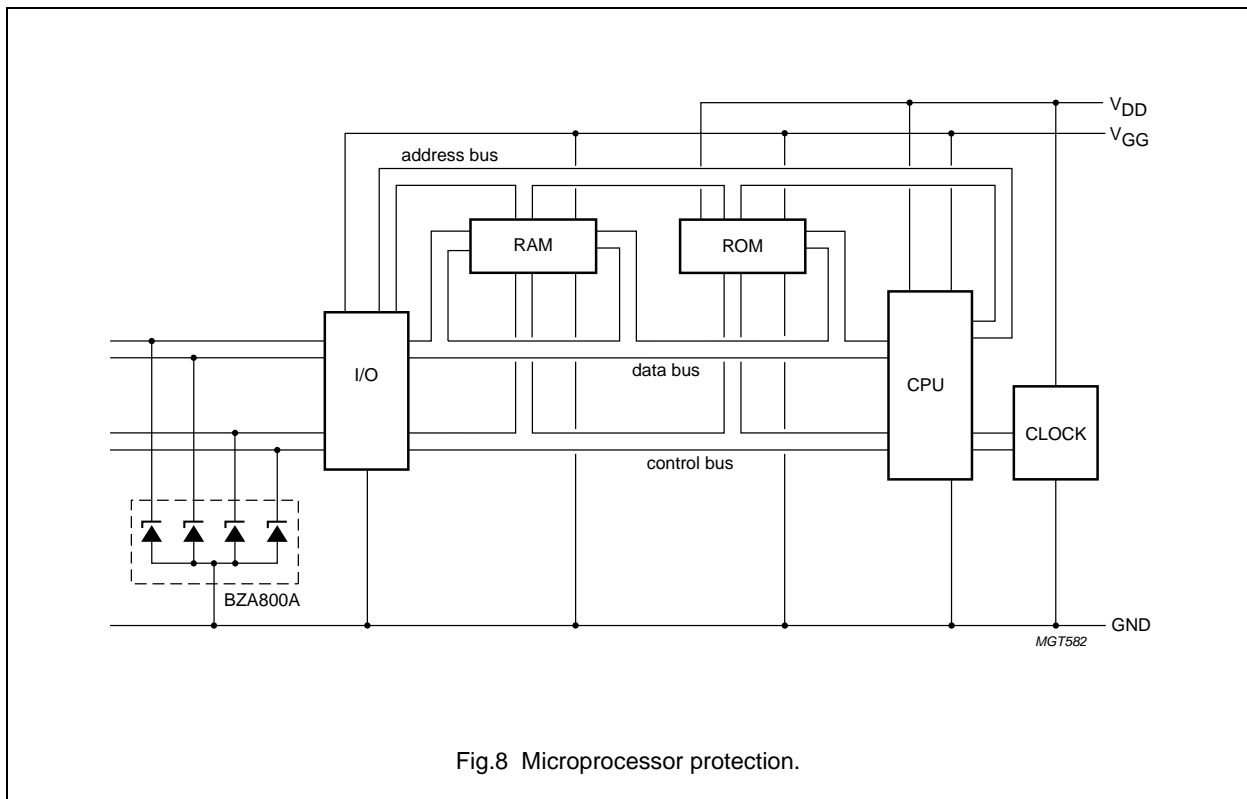
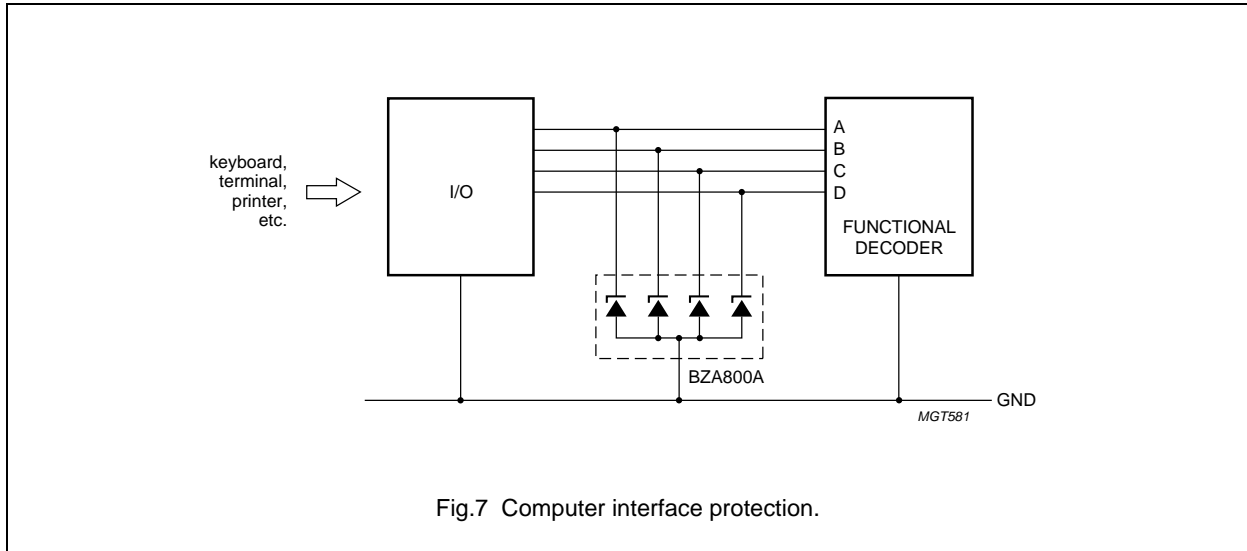
Quadruple ESD transient voltage suppressor

BZA800A-series

APPLICATION INFORMATION

Typical common anode application

A quadruple transient suppressor in a SOT353 package makes it possible to protect four separate lines using only one package. Two simplified examples are shown in Figs 7 and 8.



Quadruple ESD transient voltage suppressor

BZA800A-series

Device placement and printed-circuit board layout

Circuit board layout is of extreme importance in the suppression of transients. The clamping voltage of the BZA800A is determined by the peak transient current and the rate of rise of that current (di/dt). Since parasitic inductances can further add to the clamping voltage ($V = L di/dt$) the series conductor lengths on the printed-circuit board should be kept to a minimum. This includes the lead length of the suppression element.

In addition to minimizing conductor length the following printed-circuit board layout guidelines are recommended:

1. Place the suppression element close to the input terminals or connectors
2. Keep parallel signal paths to a minimum
3. Avoid running protection conductors in parallel with unprotected conductors
4. Minimize all printed-circuit board loop areas including power and ground loops
5. Minimize the length of the transient return path to ground
6. Avoid using shared transient return paths to a common ground point.

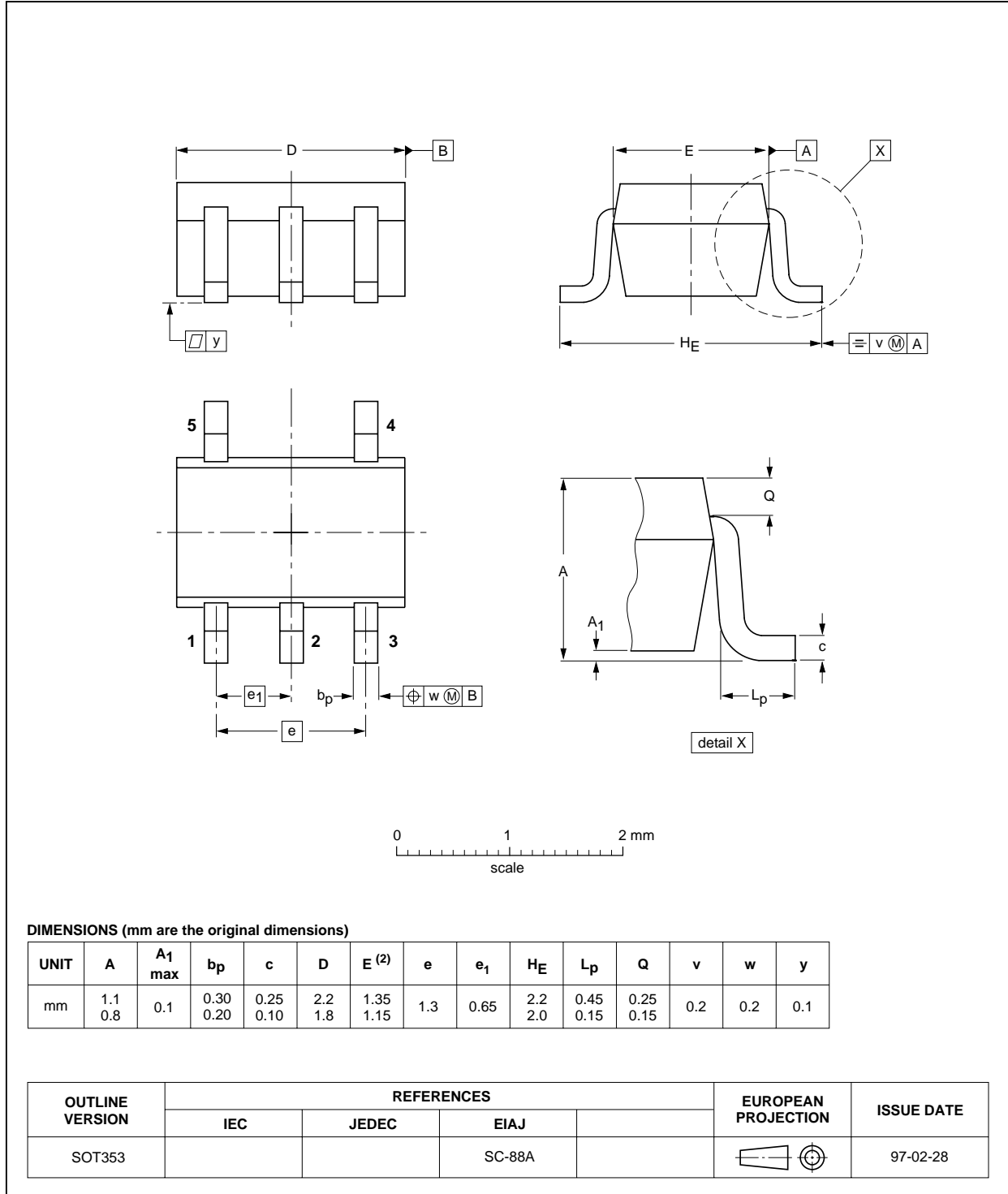
Quadruple ESD transient voltage suppressor

BZA800A-series

PACKAGE OUTLINE

Plastic surface mounted package; 5 leads

SOT353



Quadruple ESD transient voltage suppressor

BZA800A-series

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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For sales offices addresses send e-mail to: salesaddresses@nxp.com

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